

Newly developed low CTE LTCC material for ST substrates



Nippon Electric Glass

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Overview

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Motivations

Background

- Demands for ST (Space Transformer) substrates for probe cards
 - CTE of the material is close to that of silicon wafers.
 - Low electrical resistance conductors can be used.
- LTCC has an advantage over HTCC.
 - ✓ LTCC can use conductors with lower electrical resistance.

Targets

- Development of low expansion LTCC material for ST substrates
- Properties beyond existing low expansion LTCC materials
 - Bending strength
 - ✓ Fracture toughness
 - ✓ Share strength

Introduction

Raw material composition) Existing LTCC materials MLS-26 : Glass + Alumina MLS-28 : Glass + Alumina + Willemite (2ZnO • SiO₂)

	MLS-26	MLS-28
Bending strength (MPa)	375	311
Fracture toughness K _{1C} (MPa ∙ m ^{1/2})	2.3	1.9
Coefficient of thermal expansion (ppm/°C) @-40~125°C	4.7	3.7

Introduction

Raw material composition) Newly developed LTCC material New LTCC : Glass + Alumina + Cordierite (2MgO · 2Al₂O₃ · 5SiO₂)

	Cordierite	Willemite
<i>K</i> _{1C} (MPa ▪ m ^{1/2})	2.0~3.0	<1
CTE (ppm/K)	1.5~2.5	3.2

Addition of cordierite as a filler
✓ Lowering CTE of LTCC by adding small amounts
✓ Increase of fracture toughness of LTCC

Sample preparation

Newly developed LTCC material



- Bending strength measurements (Three-point bending test)
- ✓ Fracture surface observations

SEM observation of fracture surfaces of LTCC Calculation of void area by image processing

Glass 1.5X vol% Glass 1.3X vol% Glass 1.1X vol% Glass 1.0X vol% oriziani (a defici el cà l'año Void area 1.5% Void area 3.3% Void area 6.8% **Void area 12.1%** SWTest | June 3 - 5, 2024

X: normalized glass volume fraction

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Relationship between void area, bending strength and glass volume ratio



✓ Void area decreases with increasing glass volume ratio.

Bending strength is maximum at specific glass volume ratios.

Impact of glass volume ratio on bending strength



Bending strength decreases with increasing voids (Glass 1.0X vol% region).
Bending strength is low due to the low strength of the glass itself (Glass 1.5X vol% region).

Impact of particle size of glass powders on bending strength



As the average particle size of the glass powders decreases, the void area decreases and the bending strength increases.

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XRD evaluation



Anorthite precipitates as holding time increases. Anorthite is derived from alumina, not cordierite.

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Fracture toughness evaluation





Indentation fracture method Fracture toughness was evaluated by the following equation. $K_{1C} = 0.018 \left(\frac{E}{H}\right)^{1/2} \left(\frac{P}{C^{3/2}}\right)$

E: Elastic modulus, H: Vickers hardness, P: Half of indentation length, C: Half of crack length

Impact of holding time on fracture toughness



We believe that the improved fracture toughness is due to the anorthite precipitated in the glass region.

Impact of sintering temperature and holding time on CTE



- ✓ The higher the sintering temperature, the lower the CTE.
- ✓ CTE decreases with increasing holding time.
- ✓ Decrease in CTE is attributed to the reduction of alumina with high CTE.

Results and discussion Share strength evaluation





Share strength evaluation



The shear strength of New LTCC was equivalent to MLS-26 and approximately three times that of low-expansion MLS-28.

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Summary

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A new LTCC material for ST substrates with the desired CTE, high strength, and high fracture toughness was developed.

Raw material composition

✓ Selection of cordierite, a low expansion filler

 ✓ Optimization of glass volume ratio and glass particle size Sintering conditions

Optimization of sintering temperature and holding time

	MLS-26	MLS-28	New LTCC
Bending strength (MPa)	375	311	350
Fracture toughness <i>K</i> _{1C} (MPa ⋅ m ^{1/2})	2.3	1.9	2.6
Coefficient of Thermal Expansion (ppm/°C) @-40~125°C	4.7	3.7	3.6